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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO	
10/785,615	02/24/2004	Jeffry A. Kelber	5347-223	2942	
7590 08/31/2006			EXAMINER		
Mitchell S. Bigel			DINH, TUAN T		
Myers Bigel Sibley & Sajovec, P.A. P. O. Box 37428			ART UNIT	PAPER NUMBER	
Raleigh, NC	27627		2841		
			DATE MAILED: 08/31/200	DATE MAILED: 08/31/2006	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)				
	10/785,615	KELBER ET AL.				
Office Action Summary	Examiner	Art Unit				
	Tuan T. Dinh	2841				
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply						
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING DA - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. - If NO period for reply is specified above, the maximum statutory period w - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tim rill apply and will expire SIX (6) MONTHS from a cause the application to become ARANDONE	l. ely filed the mailing date of this communication.				
Status						
Responsive to communication(s) filed on 14 Ju This action is FINAL. 2b) ☐ This Since this application is in condition for allowant closed in accordance with the practice under E	action is non-final. nce except for formal matters, pro					
Disposition of Claims						
4) Claim(s) 28-36 is/are pending in the application 4a) Of the above claim(s) is/are withdraw 5) Claim(s) is/are allowed. 6) Claim(s) 28-36 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/or Application Papers 9) The specification is objected to by the Examiner 10) The drawing(s) filed on is/are: a) acceed to a possible and any objection to the content of the specification and specification is objected to by the Examiner and specification is objected	vn from consideration. r election requirement. r. epted or b) □ objected to by the Edrawing(s) be held in abeyance. See on is required if the drawing(s) is objected to be the drawing(s).	37 CFR 1.85(a). ected to. See 37 CFR 1.121(d).				
Priority under 35 U.S.C. § 119						
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 						
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date 04/17/06.	4) Interview Summary (Paper No(s)/Mail Dai 5) Notice of Informal Pa 6) Other:	te				

DETAILED ACTION

Claims 1-27 have been canceled.

1. Applicant's election without traverse of Invention II (claims 28-36) in the reply filed on 07/14/06 is acknowledged.

Claim Rejections - 35 USC § 102

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.
- 3. Claims 28-32 are rejected under 35 U.S.C. 102(e) as being anticipated by Kim (U.S. Patent 6,800,542).

As to claim 28, Kim discloses a conductive structure as shown in figures 1-2 comprising

a first conductor (12, column 3, line 36);

a plurality of atomic layers of a second conductor (13, column 3, line 47) directly on the first conductor; and a first material (13A, 14A) directly on the plurality of atomic layers of the second conductor, remote from the first conductor, the first material being

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penetrable by the plurality of atomic layers of the second conductor relative to at least a second material other than the second conductor.

As to claim 29, Kim disclose the first conductor (12) comprises a platinum group metal (Ru), the first material comprises a halogens the second conductor comprises a metal and the second material comprises oxygen (column 4, line 52-column 5, line 16).

As to claim 30, Kim further comprising a substrate (11, column 3, line 32) on the first conductor (12), remote from the plurality of atomic layers of the second conductor (13).

As to claim 31, Kim discloses the substrate comprises an integrated circuit wafer (column 1, line 14).

As to claim 32, Kim discloses the first material comprises about a monolayer of the first material.

4. Claims 33-36 are rejected under 35 U.S.C. 102(e) as being anticipated by Park et al. (Pub No. 2005/0124154A1).

As to claims 33-36, Park et al. discloses a conductive structure as shown in figures 1-3 comprising: a substrate (300) comprised an IC wafer, paragraph [0013, line 4)

- a first layer comprising ruthenium (a barrier layer 330),
- a second layer (340) comprising a plurality of atomic layers of copper directly on the first layer comprising ruthenium (330); and

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a third layer comprising iodine (370) directly on the second layer comprising a plurality of atomic layers of copper, remote from the first layer comprising ruthenium, see column 8, paragraph [0038, lines 28-30], the third layer comprises about one monolayer of iodine.

Conclusion

5. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Marsh, Satta et al., Klauk et al., and Vaartstra disclose related art.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Tuan T. Dinh whose telephone number is 571-272-1929. The examiner can normally be reached on M-F.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kammie Cuneo can be reached on 571-272-1957. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

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Tuan Dinh

August 24, 2006.